IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Connell et al.

Serial No.: 10/706,212

Filed: November 12, 2003

For: WAFER BACK SIDE COATING TO BALANCE STRESS FROM PASSIVATION LAYER ON FRONT OF WAFER AND BE USED AS A DIE ATTACH ADHESIVE

Confirmation No.: 6326

Examiner: M. Landau

Group Art Unit: 2815

Attorney Docket No.: 2269-5083.1US

(2001-0428.01/US)

VIA ELECTRONIC FILING March 28, 2008

AMENDMENT UNDER 37 C.F.R. § 1.116

MAIL STOP AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

This amendment is in response to the Office Action of February 21, 2008 whose initial period of response is set to expire on May 21, 2008.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 8 of this paper.